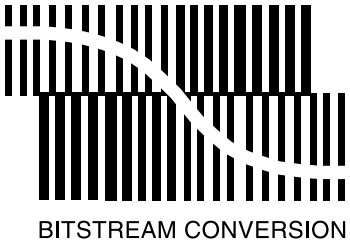
# DATA SHEET




# UDA1361TS

## 96 kHz sampling 24-bit stereo audio ADC

Product specification
Supersedes data of 2001 Jan 17

2002 Nov 25

# 96 kHz sampling 24-bit stereo audio ADC

# UDA1361TS

## FEATURES

### General

- Low power consumption
- 256, 384, 512 and 768$f_s$ system clock
- 2.4 to 3.6 V power supply
- Supports sampling frequency of 5 to 110 kHz
- Small package size (SSOP16)
- Integrated high-pass filter to cancel DC offset
- Power-down mode
- Supports 2 V (RMS) input signals
- Easy application
- Master or slave operation.

### Multiple format output interface

- $I^2S$-bus and MSB-justified format compatible
- Up to 24 significant bits serial output.

### Advanced audio configuration

- Stereo single-ended input configuration
- High linearity, dynamic range and low distortion.

BITSTREAM CONVERSION

## GENERAL DESCRIPTION

The UDA1361TS is a single chip stereo Analog-to-Digital Converter (ADC) employing bitstream conversion techniques. The low power consumption and low voltage requirements make the device eminently suitable for use in low-voltage low-power portable digital audio equipment which incorporates recording functions.

The UDA1361TS supports the $I^2S$-bus data format and the MSB-justified data format with word lengths of up to 24 bits.

## ORDERING INFORMATION

| TYPE NUMBER | PACKAGE | | |
|---|---|---|---|
| | NAME | DESCRIPTION | VERSION |
| UDA1361TS | SSOP16 | plastic shrink small outline package; 16 leads; body width 4.4 mm | SOT369-1 |

**QUICK REFERENCE DATA**

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|
| **Supplies** | | | | | | |
| $V_{DDA}$ | analog supply voltage | | 2.4 | 3.0 | 3.6 | V |
| $V_{DDD}$ | digital supply voltage | | 2.4 | 3.0 | 3.6 | V |
| $I_{DDA}$ | analog supply current | $f_s$ = 48 kHz | | | | |
| | | operating mode | – | 10.5 | – | mA |
| | | Power-down mode | – | 0.5 | – | mA |
| $I_{DDD}$ | digital supply current | $f_s$ = 48 kHz | | | | |
| | | operating mode | – | 3.5 | – | mA |
| | | Power-down mode | – | 0.45 | – | mA |
| $T_{amb}$ | ambient temperature | | −40 | – | +85 | °C |
| **Analog** | | | | | | |
| $V_{i(rms)}$ | input voltage (RMS value) | at 0 dB(FS) equivalent | – | 1.1 | – | V |
| | | at −1 dB(FS) signal output | – | 1.0 | – | V |
| (THD + N)/S | total harmonic distortion-plus-noise to signal ratio | $f_s$ = 48 kHz | | | | |
| | | at −1 dB | – | −88 | −83 | dB |
| | | at −60 dB; A-weighted | – | −40 | −34 | dB |
| | | $f_s$ = 96 kHz | | | | |
| | | at −1 dB | – | −85 | −80 | dB |
| | | at −60 dB; A-weighted | – | −40 | −37 | dB |
| S/N | signal-to-noise ratio | $V_i$ = 0 V; A-weighted | | | | |
| | | $f_s$ = 48 kHz | – | 100 | – | dB |
| | | $f_s$ = 96 kHz | – | 100 | – | dB |
| $\alpha_{cs}$ | channel separation | | – | 100 | – | dB |

## BLOCK DIAGRAM

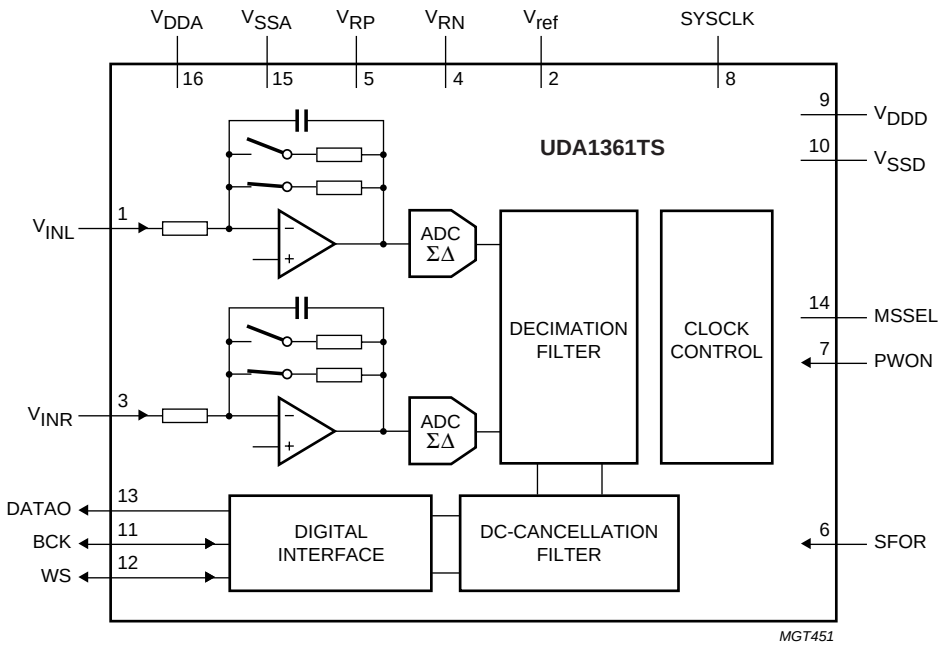



Fig.1 Block diagram.

## PINNING

| SYMBOL | PIN | DESCRIPTION |
|---|---|---|
| $V_{INL}$ | 1 | left channel input |
| $V_{ref}$ | 2 | reference voltage |
| $V_{INR}$ | 3 | right channel input |
| $V_{RN}$ | 4 | negative reference voltage |
| $V_{RP}$ | 5 | positive reference voltage |
| SFOR | 6 | data format selection input |
| PWON | 7 | power control input |
| SYSCLK | 8 | system clock 256, 384, 512 or 768$f_s$ |
| $V_{DDD}$ | 9 | digital supply voltage |
| $V_{SSD}$ | 10 | digital ground |
| BCK | 11 | bit clock input/output |
| WS | 12 | word select input/output |
| DATAO | 13 | data output |
| MSSEL | 14 | master/slave select |
| $V_{SSA}$ | 15 | analog ground |
| $V_{DDA}$ | 16 | analog supply voltage |

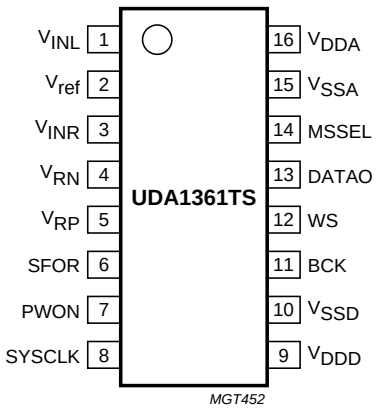



Fig.2 Pin configuration.

## FUNCTIONAL DESCRIPTION

### System clock

The UDA1361TS accommodates master and slave modes. The system devices must provide the system clock regardless of master or slave mode. In the master mode a system clock frequency of $256f_s$ is required. In the slave mode a system frequency of 256, 384, 512 or $768f_s$ is automatically detected (for a system clock of $768f_s$ the sampling frequency must be limited to 55 kHz). The system clock must be locked in frequency to the digital interface input signals.

### Input level

The overall system gain is proportional to $V_{DDA}$, or more accurately the potential difference between the reference voltages $V_{VRP}$ and $V_{VRN}$. The −1 dB input level at which THD + N/S is specified corresponds to −1 dB(FS) digital output (relative to the full-scale swing). With an input gain switch, the input level can be calculated as follows:

at 0 dB gain: $V_i(-1\ \text{dB}) = \frac{V_{VRP} - V_{VRN}}{3} = V\ (\text{RMS})$

at 6 dB gain: $V_i(-1\ \text{dB}) = \frac{V_{VRP} - V_{VRN}}{2 \times 3} = V\ (\text{RMS})$

In applications where a 2 V (RMS) input signal is used, a 12 kΩ resistor must be connected in series with the input of the ADC. This forms a voltage divider together with the internal ADC resistor and ensures that only 1 V (RMS) maximum is input to the IC.

Using this application for a 2 V (RMS) input signal, the gain switch must be set to 0 dB. When a 1 V (RMS) input signal is input to the ADC in the same application the gain switch must be set to 6 dB.

An overview of the maximum input voltage allowed against the presence of an external resistor and the setting of the gain switch is given in Table 1. The power supply voltage is assumed to be 3 V.

**Table 1** Application modes using input gain stage

| RESISTOR (12 kΩ) | INPUT GAIN SWITCH | MAXIMUM INPUT VOLTAGE (RMS) |
|---|---|---|
| Present | 0 dB | 2 V |
| Present | 0 dB | 1 V |
| Absent | 0 dB | 1 V |
| Absent | 6 dB | 0.5 V |

### Multiple format output interface

The serial interface provides the following data output formats in both master and slave modes (see Figs 3, 4 and 5):

- $I^2S$-bus with data word length of up to 24 bits
- MSB-justified serial format with data word length of up to 24 bits.

The master mode drives pins WS (word select; $1f_s$) and BCK (bit clock; $64f_s$). WS and BCK are received in slave mode.

**Table 2** Master/slave select

| MSSEL | MASTER/SLAVE SELECT |
|---|---|
| L | slave mode |
| H | master mode |
| M | (reserved for digital test) |

**Table 3** Select data format

| SFOR | DATA FORMAT |
|---|---|
| L | $I^2S$-bus data format |
| H | MSB-justified data format |
| M | (reserved for analog test) |

### Decimation filter

The decimation from $64f_s$ is performed in two stages. The first stage realizes a 4th-order sinx/x characteristic. This filter decreases the sample rate by 8.

The second stage, a FIR filter, consists of 3 half-band filters, each decimating by a factor of 2.

**Table 4** Decimation filter characteristic

| ITEM | CONDITION | VALUE (dB) |
|---|---|---|
| Pass-band ripple | 0 to 0.45$f_s$ | ±0.01 |
| Pass-band droop | 0.45$f_s$ | −0.2 |
| Stop band | >0.55 $f_s$ | −70 |
| Dynamic range | 0 to 0.45 $f_s$ | >135 |

### DC cancellation filter

A IIR high-pass filter is provided to remove unwanted DC components. The filter characteristics are given in Table 5.

**Table 5** DC cancellation filter characteristic

| ITEM | CONDITION | VALUE (dB) |
|---|---|---|
| Pass-band ripple | – | none |
| Pass-band gain | – | 0 |
| Droop | at 0.00045$f_s$ | −0.031 |
| Attenuation at DC | at 0.00000036$f_s$ | >40 |
| Dynamic range | 0 to 0.45$f_s$ | >135 |

### Mute

On recovery from Power-down, the serial data output DATAO is held LOW until valid data is available from the decimation filter. This time tracks with the sampling frequency:

$t = \frac{12288}{f_s}$, t = 256 ms when $f_s$ = 48 kHz.

### Power-down mode/input voltage control

The PWON pin can control the power saving together with the optional gain switch for 2 or 1 V (RMS) input.

The UDA1361TS supports 2 V (RMS) input using a series resistor of 12 kΩ. For the definition of the pin settings for 1 or 2 V (RMS) mode, it is assumed that this resistor is present as a default component.

**Table 6** Power-down/input voltage control

| PWON | POWER-DOWN OR GAIN |
|---|---|
| L | Power-down mode |
| M | 0 dB gain |
| H | 6 dB gain |

### Serial interface formats

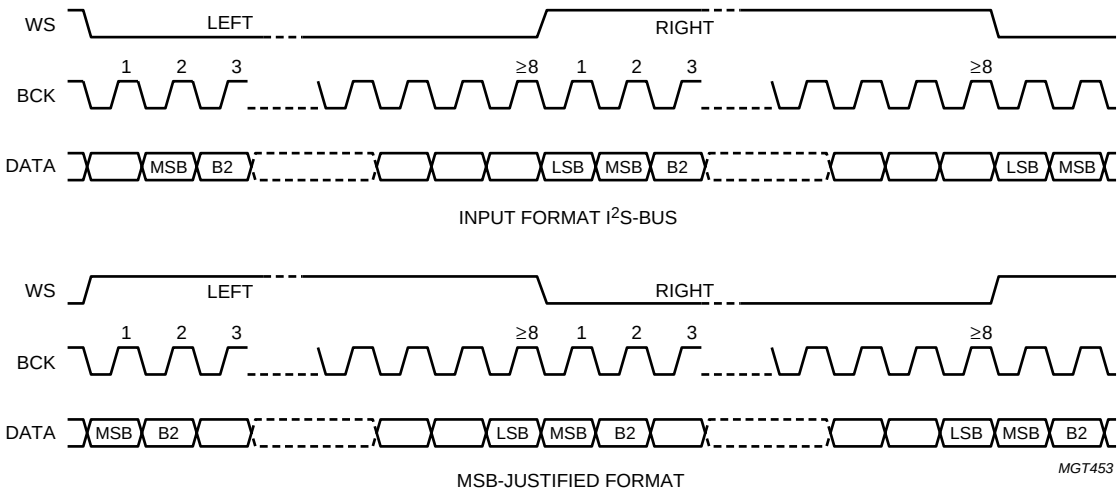



Fig.3 Serial interface formats.

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|---|---|---|---|---|---|
| $V_{DD}$ | supply voltage | note 1 | – | 4.0 | V |
| $T_{xtal(max)}$ | maximum crystal temperature | | – | 150 | °C |
| $T_{stg}$ | storage temperature | | −65 | +125 | °C |
| $T_{amb}$ | ambient temperature | | −40 | +85 | °C |
| $V_{es}$ | electrostatic handling voltage | HBM; note 2 | −3000 | +3000 | V |
| | | MM; note 2 | −300 | +300 | V |

**Notes**

1. All supply connections must be made to the same power supply.
2. ESD behaviour is tested in accordance with JEDEC II standard:
   a) Human Body Model (HBM); equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.
   b) Machine Model (MM); equivalent to discharging a 200 pF capacitor through a 0.75 μH series inductor.

### THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---|---|---|---|---|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | 130 | K/W |

### DC CHARACTERISTICS

$V_{DDD} = V_{DDA} = 3$ V; $T_{amb} = 25$ °C; all voltages referenced to ground (pins 10 and 15); unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|
| **Supplies** | | | | | | |
| $V_{DDA}$ | analog supply voltage | note 1 | 2.4 | 3.0 | 3.6 | V |
| $V_{DDD}$ | digital supply voltage | note 1 | 2.4 | 3.0 | 3.6 | V |
| $I_{DDA}$ | analog supply current | $f_s$ = 48 kHz | | | | |
| | | operating mode | – | 10.5 | – | mA |
| | | Power-down mode | – | 0.5 | – | mA |
| | | $f_s$ = 96 kHz | | | | |
| | | operating mode | – | 10.5 | – | mA |
| | | Power-down mode | – | 0.5 | – | mA |
| $I_{DDD}$ | digital supply current | $f_s$ = 48 kHz | | | | |
| | | operating mode | – | 3.5 | – | mA |
| | | Power-down mode | – | 0.45 | – | mA |
| | | $f_s$ = 96 kHz | | | | |
| | | operating mode | – | 7.0 | – | mA |
| | | Power-down mode | – | 0.65 | – | mA |

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|
| **Digital input pin (SYSCLK)** | | | | | | |
| $V_{IH}$ | HIGH-level input voltage | | 2.0 | – | 5.5 | V |
| $V_{IL}$ | LOW-level input voltage | | –0.5 | – | +0.8 | V |
| $\|I_{LI}\|$ | input leakage current | | – | – | 1 | μA |
| $C_i$ | input capacitance | | – | – | 10 | pF |
| **Digital 3-level input pins (PWON, SFOR, MSSEL)** | | | | | | |
| $V_{IH}$ | HIGH-level input voltage | | $0.9V_{DD}$ | – | $V_{DD}$ + 0.5 | V |
| $V_{IM}$ | MIDDLE-level input voltage | | $0.4V_{DD}$ | – | $0.6V_{DD}$ | V |
| $V_{IL}$ | LOW-level input voltage | | –0.5 | – | +0.4 | V |
| **Digital input/output pins (BCK, WS)** | | | | | | |
| $V_{IH}$ | HIGH-level input voltage | | 2.0 | – | 5.5 | V |
| $V_{IL}$ | LOW-level input voltage | | –0.5 | – | +0.8 | V |
| $\|I_{LI}\|$ | input leakage current | | – | – | 1 | μA |
| $C_i$ | input capacitance | | – | – | 10 | pF |
| $V_{OH}$ | HIGH-level output voltage | $I_{OH}$ = −2 mA | $0.85V_{DDD}$ | – | – | V |
| $V_{OL}$ | LOW-level output voltage | $I_{OL}$ = 2 mA | – | – | 0.4 | V |
| **Digital output pin (DATAO)** | | | | | | |
| $V_{OH}$ | HIGH-level output voltage | $I_{OH}$ = −2 mA | $0.85V_{DDD}$ | – | – | V |
| $V_{OL}$ | LOW-level output voltage | $I_{OL}$ = 2 mA | – | – | 0.4 | V |
| **Analog** | | | | | | |
| $V_{ref}$ | reference voltage | with respect to $V_{SSA}$ | $0.45V_{DDA}$ | $0.5V_{DDA}$ | $0.55V_{DDA}$ | V |
| $R_i$ | input resistance | | – | 12 | – | kΩ |
| $C_i$ | input capacitance | | – | 20 | – | pF |

**Note**

1. All power supply connections must be connected to the same external power supply unit.

**AC CHARACTERISTICS (ANALOG)**

$V_{DDD} = V_{DDA} = 3$ V; $f_i = 1$ kHz; $T_{amb} = 25$ °C; all voltages referenced to ground (pins 10 and 15); unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|
| $V_{i(rms)}$ | input voltage (RMS value) | at 0 dB(FS) equivalent | 1.1 | – | V |
| | | at −1 dB(FS) signal output | 1.0 | – | V |
| $\lvert\Delta V_i\rvert$ | unbalance between channels | | <0.1 | 0.4 | dB |
| (THD + N)/S | total harmonic distortion-plus-noise to signal ratio | $f_s$ = 48 kHz | | | |
| | | at −1 dB | −88 | −83 | dB |
| | | at −60 dB; A-weighted | −40 | −34 | dB |
| | | $f_s$ = 96 kHz | | | |
| | | at −1 dB | −85 | −80 | dB |
| | | at −60 dB; A-weighted | −40 | −37 | dB |
| S/N | signal-to-noise ratio | $V_i$ = 0 V; A-weighted | | | |
| | | $f_s$ = 48 kHz | 100 | – | dB |
| | | $f_s$ = 96 kHz | 100 | – | dB |
| $\alpha_{cs}$ | channel separation | | 100 | – | dB |
| PSRR | power supply rejection ratio | $f_{ripple}$ = 1 kHz; $V_{ripple}$ = 30 mV (p-p) | 30 | – | dB |

**AC CHARACTERISTICS (DIGITAL)**

$V_{DDD}$ = $V_{DDA}$ = 2.4 to 3.6 V; $T_{amb}$ = −40 to +85 °C; all voltages referenced to ground (pins 10 and 15); unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|
| **System clock timing** | | | | | | |
| $T_{sys}$ | system clock cycle | $f_{sys} = 256f_s$ | 35 | 88 | 780 | ns |
| | | $f_{sys} = 384f_s$ | 23 | 59 | 520 | ns |
| | | $f_{sys} = 512f_s$ | 17 | 44 | 390 | ns |
| | | $f_{sys} = 768f_s$ | 17 | 30 | 260 | ns |
| $t_{CWL}$ | LOW-level system clock pulse width | | $0.40T_{sys}$ | – | $0.60T_{sys}$ | ns |
| $t_{CWH}$ | HIGH-level system clock pulse width | | $0.40T_{sys}$ | – | $0.60T_{sys}$ | ns |
| **Serial data timing;** see Figs 4 and 5 | | | | | | |
| $T_{cy(CLK)(bit)}$ | bit clock period | $f_{cy} = \frac{1}{T_{cy}}$; master mode | $64f_s$ | $64f_s$ | $64f_s$ | Hz |
| | | $f_{cy} = \frac{1}{T_{cy}}$; slave mode | – | – | $64f_s$ | Hz |
| $t_{BCKH}$ | bit clock HIGH time | | 50 | – | – | ns |
| $t_{BCKL}$ | bit clock LOW time | | 50 | – | – | ns |
| $t_r$ | rise time | | – | – | 20 | ns |
| $t_f$ | fall time | | – | – | 20 | ns |
| $t_{d(o)(D)(BCK)}$ | data output delay time (from BCK falling edge) | | – | – | 40 | ns |
| $t_{d(o)(D)(WS)}$ | data output delay time (from WS edge) | MSB-justified format | – | – | 40 | ns |
| $t_{h(o)(D)}$ | data output hold time | | 0 | – | – | ns |
| $t_{r(WS)}$ | word select rise time | | – | – | 20 | ns |
| $t_{f(WS)}$ | word select fall time | | – | – | 20 | ns |
| $f_{WS}$ | word select period | | 1 | 1 | 1 | $f_s$ |
| $t_{d(WS)(BCK)}$ | word select delay from BCK | master mode | −40 | – | +40 | ns |
| $t_{su(WS)}$ | word select set-up time | slave mode | 20 | – | – | ns |
| $t_{h(WS)}$ | word select hold time | slave mode | 10 | – | – | ns |

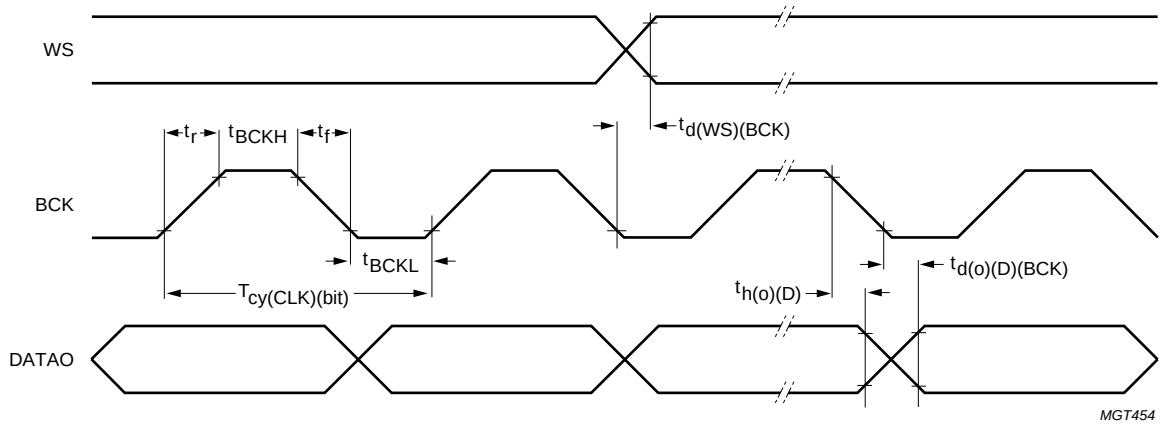



Fig.4 Serial interface master mode timing.

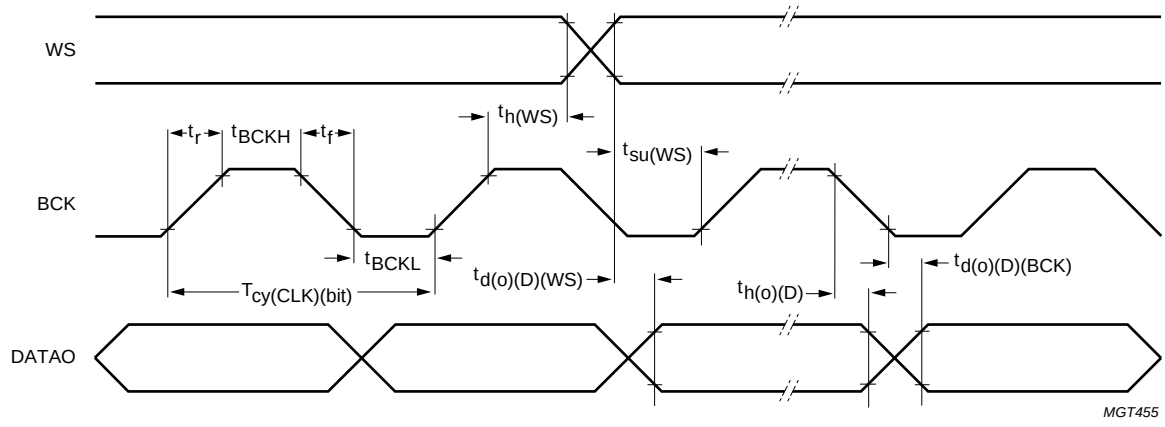
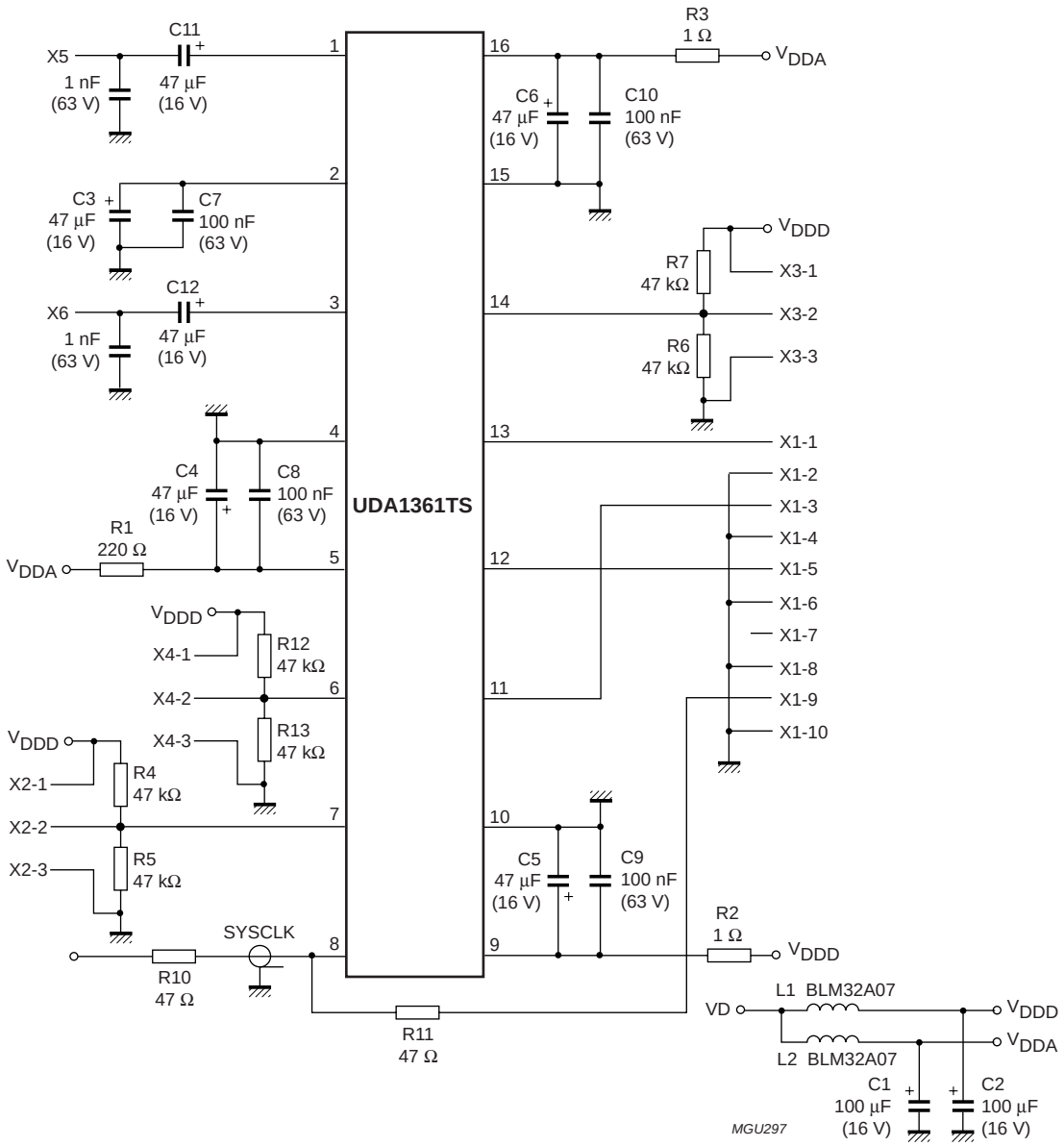



Fig.5 Serial interface slave mode timing.

## APPLICATION INFORMATION

The application information illustrated in Fig.6, is an optimum application environment. Simplification is possible at the cost of some performance degradation.

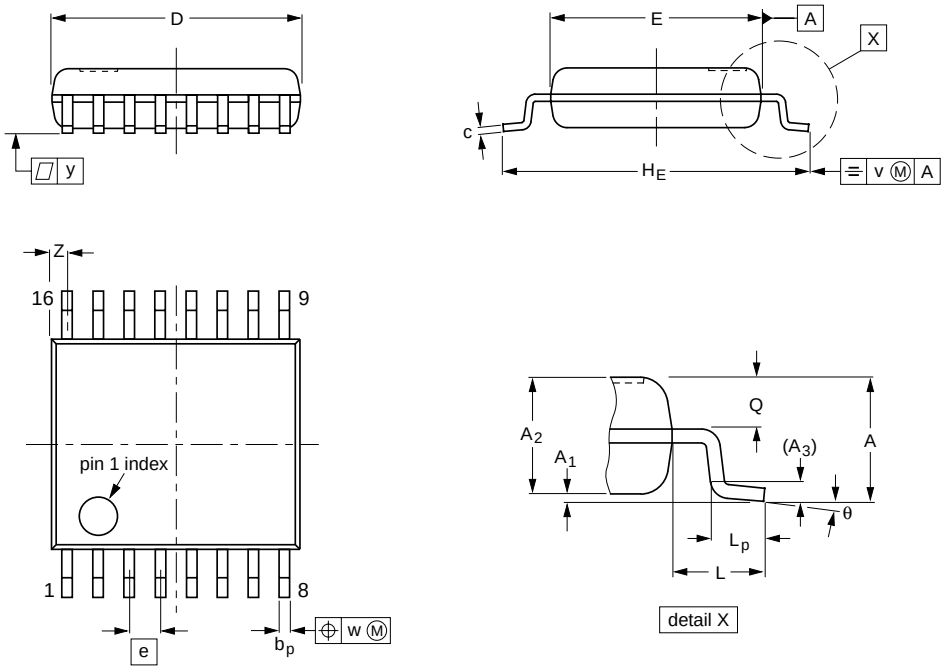


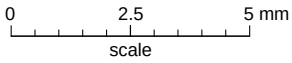

The value of capacitors C11 and C12 can be reduced. Note that changing their value will change the cut-off frequency determined by the capacitor value and the12 kΩ input resistance of the ADC.

Fig.6 Application diagram.

## PACKAGE OUTLINE

**SSOP16: plastic shrink small outline package; 16 leads; body width 4.4 mm** **SOT369-1**




**DIMENSIONS (mm are the original dimensions)**

| UNIT | A max. | $A_1$ | $A_2$ | $A_3$ | $b_p$ | c | $D^{(1)}$ | $E^{(1)}$ | e | $H_E$ | L | $L_p$ | Q | v | w | y | $Z^{(1)}$ | θ |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| mm | 1.5 | 0.15<br>0.00 | 1.4<br>1.2 | 0.25 | 0.32<br>0.20 | 0.25<br>0.13 | 5.3<br>5.1 | 4.5<br>4.3 | 0.65 | 6.6<br>6.2 | 1 | 0.75<br>0.45 | 0.65<br>0.45 | 0.2 | 0.13 | 0.1 | 0.48<br>0.18 | $10^o$<br>$0^o$ |

**Note**

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|---|---|---|---|---|---|---|
| | IEC | JEDEC | JEITA | | | |
| SOT369-1 | | MO-152 | | | | ~~99-12-27~~<br>03-02-19 |

## SOLDERING

### Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

### Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferable be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

### Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

  The footprint must incorporate solder thieves at the downstream end.
- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.
A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

### Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

**Suitability of surface mount IC packages for wave and reflow soldering methods**

| PACKAGE[1] | SOLDERING METHOD | |
|---|---|---|
| | WAVE | REFLOW[2] |
| BGA, LBGA, LFBGA, SQFP, TFBGA, VFBGA | not suitable | suitable |
| HBCC, HBGA, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, HVSON, SMS | not suitable[3] | suitable |
| PLCC[4], SO, SOJ | suitable | suitable |
| LQFP, QFP, TQFP | not recommended[4][5] | suitable |
| SSOP, TSSOP, VSO | not recommended[6] | suitable |

**Notes**

1. For more detailed information on the BGA packages refer to the *"(LF)BGA Application Note*" (AN01026); order a copy from your NXP Semiconductors sales office.
2. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.
3. These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
5. Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
6. Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

**DATA SHEET STATUS**

| DOCUMENT STATUS[1] | PRODUCT STATUS[2] | DEFINITION |
|---|---|---|
| Objective data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

**Notes**

1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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**Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

**Contact information**

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